

Abstracts

Ka band power pHEMT technology for space power flip-chip assembly

E. Rogeaux, J.-P. Fraysse, C. Schaffauser, S. George, D. Pons, P. Fellon, D. Geiger, D. Theron, N. Haese, S. Verdeyme, R. Quere, D. Baillargeat, E. Ngoya, S. Long and L. Escotte. "Ka band power pHEMT technology for space power flip-chip assembly." 2001 MTT-S International Microwave Symposium Digest 01.3 (2001 Vol. III [MWSYM]): 1895-1898 vol.3.

This paper proposes a released power pHEMT process for flip-chip mounting. The potential of this flip-chip process is demonstrated for power and low-noise applications in Ka-band.

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